



(12) **EUROPEAN PATENT APPLICATION**

(43) Date of publication:
08.10.2014 Bulletin 2014/41

(51) Int Cl.:
G02B 6/138 (2006.01) **G02B 6/12 (2006.01)**
G02B 6/42 (2006.01)

(21) Application number: **14162345.4**

(22) Date of filing: **28.03.2014**

(84) Designated Contracting States:
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR
 Designated Extension States:
BA ME

(72) Inventors:
 • **SchellL, Andreas**
10245 Berlin (DE)
 • **Fischer, Joachim**
77876 Kappelrodeck (DE)
 • **Kaschke, Johannes**
76137 Karlsruhe (DE)
 • **Wegener, Martin**
76227 Karlsruhe (DE)
 • **Benson, Oliver**
12203 Berlin (DE)

(30) Priority: **04.04.2013 US 201313856621**

(71) Applicants:
 • **Humboldt Universität zu Berlin**
10099 Berlin (DE)
 • **Karlsruher Institut für Technologie**
76131 Karlsruhe (DE)

(74) Representative: **Fischer, Uwe**
Patentanwalt
Moritzstraße 22
13597 Berlin (DE)

(54) **Methods and fabrication tools for fabricating optical devices**

(57) An embodiment of the present invention relates to a method of fabricating an optical device, the method comprising the steps of:

- depositing a photoresist layer (20) on a carrier (101), said photoresist layer containing at least one optical component (30, 40),
- determining the position of the at least one optical component inside the photoresist layer before exposing the photoresist layer to a first radiation (λ_1), said first radiation being capable of transforming the photoresist layer from an unmodified state to a modified state,
- elaborating a device pattern based on the position of the at least one optical component, and
- fabricating the elaborated device pattern by locally exposing the photoresist layer to the first radiation and locally transforming the photoresist layer from the unmodified state to the modified state.

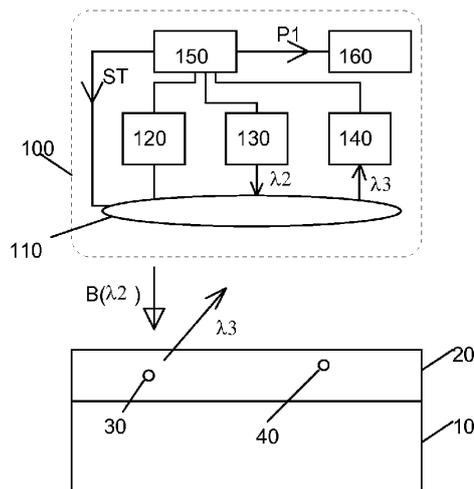


Fig. 4

Description

[0001] The invention relates to methods and fabrication tools for fabricating optical devices, in particular devices which comprise single photon emitters.

Background of the invention

[0002] On-chip photonic circuits working at the single-quantum level play an important role for future quantum information processing [1]. Several approaches to assemble such quantum photonic devices from different fundamental photonic entities have been pursued [2]. For example, by using self-assembled quantum dots in semiconductor membranes, one can exploit the full power of semiconductor nanofabrication technology, and sophisticated structures have been demonstrated [1], even with on-demand coupling architectures [3]. However, this approach is limited to two-dimensional structures, except for few results obtained by extremely challenging manual membrane-stacking [4].

[0003] Another easy and low-cost way of fabricating photonic structures is optical lithography via direct laser writing (DLW) [5, 6] where a tightly focussed femtosecond laser beam is used to expose a photoresist. The use of multi-photon absorption enables a sequential 3D exposure by scanning the sample or the focus of the laser. For common negative-tone photoresists, unexposed parts are removed during a development step and the 3D polymer structures remain. DLW is well known for the fabrication of photonic crystals [6] or other photonic elements like resonators [7, 8] and waveguides [9]. In order to functionalise the structures with optically active material, fluorescent dyes [10], quantum dots [11] and metal nanoparticles [12] have been incorporated. However, until today there has been no 3D structure operating at the fundamental quantum level with single photons from single emitters being collected and routed. Moreover, no combinations of multiple optical elements (different resonators, couplers, waveguides) have been demonstrated. The reason is the lack of photostable quantum emitters which are compatible with the DLW process while still preserving the possibility for high-quality DLW fabrication.

Objective of the present invention

[0004] An objective of the present invention is to provide reliable methods and tools for fabricating optical devices that are difficult to handle, for instance small optical components such as single photon emitters.

Brief summary of the invention

[0005] An embodiment of the present invention relates to a method of fabricating an optical device, the method comprising the steps of:

- depositing a photoresist layer on a carrier, said photoresist layer containing at least one optical component,
- determining the position of the at least one optical component inside the photoresist layer before exposing the photoresist layer to a first radiation, said first radiation being capable of transforming the photoresist layer from an unmodified state to a modified state,
- elaborating a device pattern based on the position of the at least one optical component, and
- fabricating the elaborated device pattern by locally exposing the photoresist layer to the first radiation and locally transforming the photoresist layer from the unmodified state to the modified state.

[0006] An advantage of this embodiment of the invention is that there is no need to apply any measures to guarantee a predefined location of the optical component on the carrier before the photoresist is deposited. The position of the optical component is not relevant and may vary in a wide range because the location of the optical component may be determined and evaluated after the photoresist is deposited.

[0007] Furthermore, the step of locally exposing the photoresist layer to radiation (herein referred to as first radiation that transforms the photoresist layer from an unmodified state to a modified state) can be carried out using the same optical system that is used to locate the optical component on the carrier. Therefore, misalignment errors can be avoided or at least significantly minimized.

[0008] The at least one optical component may be a single photon emitter.

[0009] The step of determining the position of the at least one optical component inside the photoresist layer preferably includes:

- generating a second radiation that is incapable of transforming the photoresist layer from the unmodified state to the modified state, and
- observing the response of the at least one optical component to the second radiation.

[0010] The at least one optical component may be adapted to generate a third radiation in response to being exposed to the second radiation. Said step of observing the response of the at least one optical component may include detecting and/or evaluating the third radiation. The photoresist is preferably unresponsive to the third radiation.

[0011] According to a further preferred embodiment of the present invention the method further comprises the step of locally polymerizing the photoresist layer by locally exposing the photoresist layer to the first radiation, the polymerized photoresist being transparent for radiation that is generated by the optical component and/or transparent to radiation that excites the optical compo-

nent to generate radiation.

[0012] The device pattern may be fabricated by selectively exposing those sections of the photoresist layer that correspond to sections of the elaborated device pattern.

[0013] The photoresist layer may contain at least two optical components. The position of the first optical component and the position of the second optical component are preferably determined inside the photoresist layer before exposing the photoresist layer to the first radiation. Then, a connection pattern may be elaborated that provides a future physical connection between the first optical component and the second optical component. The connection pattern may be fabricated by selectively exposing those sections of the photoresist layer that correspond to sections of the elaborated connection pattern.

[0014] The physical connection is preferably an optical connection for transmitting optical radiation between the first and second optical components.

[0015] Alternatively, the photoresist layer may contain a plurality of optical components. In this case, a connection pattern may be elaborated that provides a future physical connection between at least a group of optical elements out of said plurality of optical components. The connection pattern may be fabricated by selectively exposing those sections of the photoresist layer that correspond to sections of the elaborated connection pattern, and by developing the photoresist layer.

[0016] The step of determining the position of the at least one optical component and said step of fabricating the device pattern is preferably carried out using the same optical system. Preferably, the same microscope is used for determining the position of the at least one optical component and for applying the first radiation to the photoresist layer. Using the same optical system helps to avoid misalignment errors and increases the success rate or gain of the fabrication process.

[0017] According to a preferred embodiment, the same confocal microscope is used for the following steps:

- generating the second radiation,
- observing the response of the at least one optical component to the second radiation,
- detecting and/or evaluating a third radiation generated by the at least one optical component in response to being exposed to the second radiation, and
- locally exposing the photoresist layer to the first radiation and locally transforming the photoresist layer from the unmodified state to the modified state.

[0018] The photoresist may be polymerized in response to exposure to the first radiation. The polymerized photoresist may be transparent for radiation that is generated by the optical device. For instance, the polymerized photoresist is preferably also transparent for a second radiation and a third radiation wherein the second radiation is capable of exciting the optical device to gen-

erate a third radiation, and wherein the third radiation is generated by the optical device while being excited by the second radiation.

[0019] After determining the position of the at least one optical component inside the photoresist layer and before exposing the photoresist layer to said first radiation, the position of the at least one optical component may be changed by applying a fourth radiation.

[0020] A further embodiment of the present invention relates to a method comprising the steps of:

- depositing a photoresist layer on a carrier, said photoresist layer comprising at least one optical component,
- determining the position of the at least one optical component inside the photoresist layer before exposing the photoresist layer to radiation having a wavelength and/or pulse pattern that is capable of transforming the photoresist layer from an unmodified state to a modified state,
- elaborating a device pattern based on the position of the at least one optical component, and
- fabricating the elaborated device pattern by locally exposing the photoresist layer to the radiation and locally transforming the photoresist layer from the unmodified state to the modified state.

[0021] Said step of determining the position of the at least one optical component inside the photoresist layer preferably includes:

- generating a radiation having a second wavelength and/or pulse pattern that is incapable of transforming the photoresist layer from the unmodified state to the modified state, and
- observing the response of the at least one optical component to the radiation of the second wavelength and/or pulse pattern.

[0022] Said at least one optical component is preferably adapted to generate a radiation of a third wavelength in response to being exposed to the radiation of the second wavelength and/or pulse pattern, said emitted radiation of the third wavelength being incapable of transforming the photoresist layer from the unmodified state to the modified state.

[0023] Said step of observing the response of the at least one optical component preferably includes detecting and/or evaluating the radiation of the third wavelength.

[0024] A further embodiment of the present invention relates to a method comprising the steps of:

- depositing a photoresist layer on a carrier, said photoresist layer comprising at least one optical single photon emitter,
- determining the position of the at least one optical single photon emitter inside the photoresist layer be-

fore locally exposing the photoresist layer to radiation that is capable of polymerizing the photoresist layer,

- elaborating a device pattern depending on the position of the at least one optical single photon emitter, and
- fabricating the elaborated device pattern by locally polymerizing the photoresist layer by locally exposing the photoresist layer to said radiation, and developing the photoresist layer.

[0025] A further embodiment of the present invention relates to a fabrication tool comprising:

- a first emitter unit capable of generating a first radiation capable of transforming a photoresist layer from an unmodified state to a modified state,
- a second emitter unit capable of generating a second radiation capable of exciting optical components inside the photoresist layer to generate a third radiation,
- a detector capable of detecting the third radiation,
- an optical system adapted to direct radiation generated by the first emitter unit and/or the second emitter unit onto the photoresist layer, and
- a processor unit for controlling the optical system, the first emitter unit, and the second emitter unit,
- wherein the processor unit is configured to determine the positions of the optical components inside the photoresist layer, to elaborate a device pattern based on the positions of the optical components, and to fabricate the elaborated device pattern by locally exposing the photoresist layer to the first radiation.

Brief description of the drawings

[0026] In order that the manner in which the above-recited and other advantages of the invention are obtained will be readily understood, a more particular description of the invention briefly described above will be rendered by reference to specific embodiments thereof which are illustrated in the appended figures. Understanding that these figures depict only typical embodiments of the invention and are therefore not to be considered to be limiting of its scope, the invention will be described and explained with additional specificity and detail by the use of the accompanying drawings in which

Figures 1-9 show - in exemplary fashion - fabrication steps for fabricating an optical device, and an exemplary embodiment of a fabrication tool for carrying out the steps shown in Figures 1-9,

Figures 10-11 show modified fabrication steps for fabricating a 3D-photoresist pattern,

Figures 12-13 show additional fabrication steps for freezing the positions of optical components inside a photoresist layer, and

5 Figure 14 shows an additional fabrication step for moving optical components inside a photoresist layer before exposure and development of the photoresist layer.

10 Detailed description of the preferred embodiments

[0027] The preferred embodiments of the present invention will be best understood by reference to the drawings, wherein identical or comparable parts are designated by the same reference signs throughout. It will be readily understood that the present invention, as generally described herein, could vary in a wide range. Thus, the following more detailed description of the exemplary embodiments of the present invention, is not intended to limit the scope of the invention, as claimed, but is merely representative of presently preferred embodiments of the invention.

[0028] An exemplary embodiment of a method for fabricating an optical device 300 (see Figure 9) will be explained hereinafter with reference to Figures 1-9.

[0029] Figure 1 shows a carrier 10 (e. g. a silicon carrier) after depositing a photoresist layer 20 thereon. The photoresist layer 20 contains a plurality of optical components, for instance at least two single photon emitters which are marked by reference numerals 30 and 40 in Figure 1.

[0030] The photoresist layer 20 may be based on monomer pentaerythritol tetraacrylate (PETTA) which may contain 350 ppm monomethyl ether hydroquinone as inhibitor. 0.25 % wt of photoinitiator 7-diethylamino-3-thenoylcoumarin may be added.

[0031] The single photon emitters 30 and 40 may be imbedded in the photoresist by adding 2 % wt of an ethanol-based nanodiamond suspension and by stirring the mixture. The nanodiamonds may be of type 1b and may have a median diameter of approximately 25 nm. Such nanodiamonds are available from Microdiamant AG.

[0032] Alternative photoresists include any negative-tone photoresist based on free radical polymerization, cationic polymerization, or other polymerization chemistries (e.g., Thiol-Ene reactions). A wide variety of polymerizable substances (monomers, oligomers, pre-polymers) is applicable. Among commercially available photoresists, SU-8 (Microchem Corp.) or photoresists out of the ORMOCER class (Fraunhofer ISC) are potential candidates.

[0033] Alternative single photon emitters include various defect centers in nanocrystals from materials like Silicon, Silicon Carbide, Zinc Oxide and quantum dot structures made of semiconductors like Zinc Selenide and Cadmium Selenide.

[0034] The photoresist layer 20 may be dried or thermally treated in order to increase its mechanical stability

and prevent the single photon emitters 30 and 40 from drifting inside the photoresist layer 20. However, such an additional treatment is not mandatory.

[0035] The single photon emitters 30 and 40 are capable of generating radiation in response to radiation they receive. This will be explained in further detail below.

[0036] In order to fabricate a photoresist pattern and a device pattern that includes both single photon emitters 30 and 40, a fabrication tool in form of an exposure and detection device 100 as shown in Figure 2 may be used. The exposure and detection device 100 preferably comprises an optical system 110, a first emitter unit 120, a second emitter unit 130, a detector 140, and a processor unit 150.

[0037] The first emitter unit 120 is capable of generating a first radiation λ_1 having a wavelength or wavelength range that can transform the photoresist layer 20 from an unmodified state to a modified state. Preferably, the first radiation λ_1 is able to polymerize the photoresist layer 20. In case of a photoresist layer made of monomer pentaerythritol tetraacrylate (PETTA) as described above, the first radiation λ_1 preferably includes a wavelength of 800 nm and may be pulsed.

[0038] The second emitter unit 130 can generate a second radiation λ_2 having a wavelength or wavelength range that cannot transform the photoresist layer 20 from the unmodified state to the modified state. Instead, the second radiation λ_2 is capable of exciting the single photon emitters 30 and 40 to generate a third radiation λ_3 .

[0039] In case of single photon emitters based on nanodiamonds, and a photoresist layer 20 as described above, the second radiation λ_2 preferably includes a wavelength of 532 nm. If illuminated by such a radiation, nanodiamonds typically generate radiation having a wavelength of 700 nm. This radiation is also incapable of transforming the photoresist layer 20 from the unmodified state to the modified state due to its low power and non-absorbed wavelength.

[0040] The detector 140 is capable of detecting the third radiation λ_3 if and when such radiation is generated by the single photon emitters 30 and/or 40.

[0041] The optical system 110 may comprise or consist of a microscope such as a confocal microscope which is adapted to focus radiation generated by the first emitter unit 120 and/or the second emitter unit 130 onto the photoresist layer 20. The resulting focussed radiation beam is marked by reference sign B in Figure 2.

[0042] The relative position of the radiation beam B with respect to the underlying photoresist layer 20 may be varied by the optical system 110 in response to a control signal ST generated by the processor unit 150. The relative two-dimensional movement of the radiation beam B is indicated by arrow P in Figure 2.

[0043] The processor unit 150 is preferably configured (e. g. programmed) to control and enable the following process steps:

Before exposing the photoresist layer 20 to the first

radiation λ_1 , the positions of the single photon emitters 30 and 40 inside the photoresist layer 20 are determined. To this end, the processor unit 150 enables the second emitter unit 130 to generate the second radiation λ_2 in order to excite the single photon emitters 30 and 40 to generate the third radiation λ_3 . Since the position of the single photon emitters 30 and 40 is unknown at this stage, the second radiation λ_2 or its radiation beam B(λ_2) is scanned over the photoresist layer 20 in order to detect a response of one of the single photon emitters buried and hidden in the photoresist layer 20 (see Figure 3).

[0044] As soon as the second radiation λ_2 or its radiation beam B(λ_2) hits the single photon emitter 30, the latter generates the third radiation λ_3 which will be detected by the detector 140. This enables the processor unit 150 to determine and store the position P1 of the single photon emitter 30 in an internal or external memory 160 (see Figure 4).

[0045] Then, the processor unit 150 continues the search for the other single photon emitter 40 in order to determine its exact position (see Figure 5). When the single photon emitter 40 is excited by the second radiation λ_2 , it generates the third radiation λ_3 which in turn is detected by the detector 140 (see Figure 6). The detector 140 transmits this information to the processor unit 150 which determines and stores the corresponding position P2 of the single photon emitter 40 in the memory 160.

[0046] Thereafter, the processor unit 150 elaborates a photoresist pattern PP that will define the device pattern of the later completed optical device. The elaborated photoresist pattern PP is indicated in Figure 7 by dotted lines.

[0047] Then, the processor unit 150 initiates and controls the fabrication of the elaborated device pattern PP by locally exposing the photoresist layer 20 to the first radiation λ_1 and locally transforming the photoresist layer 20 from the unmodified state to the modified state (see Figure 8). Figure 9 shows the fabricated optical device 300 after developing the photoresist layer 20, i.e. after locally removing the unexposed regions of the photoresist layer 20.

[0048] The transition preferably includes a polymerization of the photoresist layer 20. The polymerized photoresist is preferably transparent, e.g. transparent for the second and/or the third radiation λ_2 and λ_3 . In the latter case, the polymerized photoresist may serve as a waveguide 200 or waveguide structure, which connects the two single photon emitters 30 and 40 with each other and/or with one or more other optical components. In other words, the polymerized photoresist 200 may also be useful during the future operation of the completed optical device 300.

[0049] In summary, the fabrication steps shown in Figures 1-9 yield an optical device 300 which comprises two single photon emitters 30 and 40 that are optically connected by the waveguide 200. Through this waveguide

200, radiation may be transmitted from the single photon emitter 30 to the single photon emitter 40 and vice versa.

[0050] The local exposure of the photoresist layer 20 to the first radiation λ_1 may take the thickness of the photoresist layer 20 into account. By focussing the beam $B(\lambda_1)$ onto different planes during the exposure step, three-dimensional waveguides 200' or three-dimensional waveguide structures can be fabricated. This is shown in Figures 10 and 11 which visualize the steps of elaborating a 3D-photoresist pattern PP' and therefore a 3D-device pattern, and fabricating the elaborated device pattern PP' by locally exposing the photoresist layer 20 to the first radiation λ_1 . The unexposed photoresist can then be removed in a developing step.

[0051] Furthermore, it is possible to mechanically fix or freeze the location of the single photon emitters after their position has been located. To this end, the first radiation λ_1 may be generated to locally polymerize the photoresist layer 20 in the region where the respective single photon emitter has been found before consecutive fabrication steps are initiated.

[0052] An example of the corresponding additional freezing step is shown with reference to the single photon emitter 30 in Figure 12. This additional freezing step can be carried out after determining the position of the single photon emitter 30 (see Figure 4) and before searching for the other single photon emitter 40 (see Figure 5). The polymerized and therefore "frozen" photoresist section is designated by reference sign FS in Figure 12.

[0053] In a similar fashion, the location of the single photon emitter 40 can be fixed or frozen before further steps are carried out. For instance, the first radiation λ_1 may be generated to locally polymerize the photoresist layer 20 in the region where the single photon emitter 40 has been found (see Figure 13) before the device pattern PP' is elaborated or fabricated (see Figures 10 and 11).

[0054] Further, it is possible to change the position of the single photon emitters 30 and 40 after their positions have been located. To this end, a fourth radiation λ_4 having a wavelength of 1064 nm may be generated to locally move the single photon emitters. In an exemplary fashion, Figure 14 shows the movement of the single photon emitter 30 after its position has been determined and before fixing or freezing the position (see Figure 12) and/or before continuing the search for the other single photon emitter 40 (see Figure 5) and/or before elaborating and fabricating the device pattern PP' (see Figure 10 and 11).

[0055] In order to generate the fourth radiation λ_4 the exposure and detection device 100 may include a third emitter unit 400 as shown in Figure 14.

Reference Signs

[0056]

10 carrier
20 photoresist layer

30 single photon emitter
40 single photon emitter
100 exposure and detection device
110 optical system
5 120 first emitter unit
130 second emitter unit
140 detector
150 processor unit
160 memory
10 200 waveguide
300 fabricated optical device
400 third emitter unit
 λ_1 first radiation
 λ_2 second radiation
15 λ_3 third radiation
 λ_4 fourth radiation
B beam
 $B(\lambda_1)$ beam of first radiation
 $B(\lambda_2)$ beam of second radiation
20 $B(\lambda_3)$ beam of third radiation
 $B(\lambda_4)$ beam of fourth radiation
FS polymerized section
P movement
PP photoresist pattern/device pattern
25 PP' photoresist pattern/device pattern
P1 position of single photon emitter
P2 position of single photon emitter
ST control signal

30 Literature

[0057]

- 35 [1] O'Brien, J. L., Furusawa, A., and Vuckovic, J. Photonic quantum technologies. *Nature Photon.* 3, 687{695 (2009).
- [2] Benson, O. Assembly of hybrid photonic architectures from nanophotonic constituents, *Nature* 480, 193{199 (2011).
- 40 [3] Badolato, A. et al. Deterministic coupling of single quantum dots to single nanocavity modes. *Science* 308, 1158{1161 (2005).
- 45 [4] Aoki, K. et al. Coupling of quantum-dot light emission with a three-dimensional photonic crystal nanocavity. *Nature Photon.* 2, 688{692 (2008).
- [5] Kawata, S., Sun, H. B., Tanaka, T., and Takada, K. Finer features for functional microdevices, *Nature* 412, 697{698 (2001).
- 50 [6] Deubel, M. et al. Direct laser writing of three-dimensional photonic-crystal templates for telecommunications, *Nature Mater.* 3, 444{447 (2004).
- [7] Liu, Z. P. et al. Direct laser writing of whispering

gallery microcavities by two-photon polymerization, Appl. Phys. Lett. 97, 211105{211105 (2010).

[8] Grossmann, T. et al. Direct laser writing for active and passive high-q polymer microdisks on silicon. Opt. Express 19, 11451{11456 (2011).

[9] Lee, C.-W., Pagliara, S., Keyser, U., and Baumberg, J. J. Perpendicular coupling to in-plane photonics using arc waveguides fabricated via two-photon polymerization. Appl. Phys. Lett. 100, 171102 (2012).

[10] Sun, H., Tanaka, T., Takada, K., and Kawata, S. Two-photon photopolymerization and diagnosis of three-dimensional microstructures containing uorescent dyes. Appl. Phys. Lett. 79, 1411 (2001).

[11] Li, J., Jia, B., Zhou, G., and Gu, M. Fabrication of three-dimensional woodpile photonic crystals in a PbSe quantum dot composite material. Opt. Express 14, 10740{10745 (2006).

[12] Shukla, S. et al. Subwavelength direct laser patterning of conductive gold nanostructures by simultaneous photopolymerization and photoreduction. ACS Nano 5, 1947{1957 (2011).

Claims

1. Method of fabricating an optical device, the method comprising the steps of:

- depositing a photoresist layer on a carrier, said photoresist layer containing at least one optical component,
- determining the position of the at least one optical component inside the photoresist layer before exposing the photoresist layer to a first radiation, said first radiation being capable of transforming the photoresist layer from an unmodified state to a modified state,
- elaborating a device pattern based on the position of the at least one optical component, and
- fabricating the elaborated device pattern by locally exposing the photoresist layer to the first radiation and locally transforming the photoresist layer from the unmodified state to the modified state.

2. Method of claim 1 wherein the at least one optical component is a single photon emitter.

3. Method of any of the preceding claims wherein said step of determining the position of the at least one optical component inside the photoresist layer

includes:

- generating a second radiation that is incapable of transforming the photoresist layer from the unmodified state to the modified state, and
- observing the response of the at least one optical component to the second radiation.

4. Method of claim 3 wherein

- said at least one optical component is adapted to generate a third radiation in response to being exposed to the second radiation, and
- said step of observing the response of the at least one optical component includes detecting and/or evaluating the third radiation.

5. Method of claim 4 wherein

said photoresist is unresponsive to the third radiation.

6. Method of any of the preceding claims further comprising the step of:

- locally polymerizing the photoresist layer by locally exposing the photoresist layer to the first radiation, the polymerized photoresist being transparent for radiation that is generated by the optical component and/or transparent to radiation that excites the optical component to generate radiation.

7. Method of any of the preceding claims wherein

the device pattern is fabricated by selectively exposing those sections of the photoresist layer that correspond to sections of the elaborated device pattern.

8. Method of any of the preceding claims

- wherein the photoresist layer contains at least two optical components,
- wherein the position of the first optical component and the position of the second optical component are determined inside the photoresist layer before exposing the photoresist layer to the first radiation,
- wherein a connection pattern is elaborated that provides a future physical connection between the first optical component and the second optical component, and
- wherein the connection pattern is fabricated by selectively exposing those sections of the photoresist layer that correspond to sections of the elaborated connection pattern.

9. Method of any of the preceding claims wherein the physical connection is an optical connection for transmitting optical radiation between the first and

second optical components.

10. Method of any of the preceding claims

- wherein the photoresist layer contains a plurality of optical components, 5
- wherein a connection pattern is elaborated that provides a future physical connection between at least a group of optical elements out of said plurality of optical components, and 10
- wherein the connection pattern is fabricated by selectively exposing those sections of the photoresist layer that correspond to sections of the elaborated connection pattern, and developing the photoresist layer. 15

11. Method of claim any of the preceding claims wherein said step of determining the position of the at least one optical component and said step of fabricating the device pattern are carried out using the same optical system. 20

12. Method of any of the preceding claims wherein the photoresist is polymerized in response to exposure to the first radiation, the polymerized photoresist being transparent for radiation that is generated by the optical device. 25

13. Method of any of the preceding claims wherein the photoresist is polymerized in response to exposure to the first radiation, the polymerized photoresist being transparent for each of the following radiations: 30

- a second radiation that is capable of exciting the optical device to generate a third radiation, and 35
- the third radiation that is generated by the optical device while being excited by the second radiation. 40

14. Method of any of the preceding claims wherein

- after determining the position of the at least one optical component inside the photoresist layer and before exposing the photoresist layer to said first radiation, the position of the at least one optical component is changed by applying a fourth radiation. 45

15. Fabrication tool comprising: 50

- a first emitter unit capable of generating a first radiation capable of transforming a photoresist layer from an unmodified state to a modified state, 55
- a second emitter unit capable of generating a second radiation capable of exciting optical components inside the photoresist layer to gen-

erate a third radiation,

- a detector capable of detecting the third radiation,

- an optical system adapted to direct radiation generated by the first emitter unit and/or the second emitter unit onto the photoresist layer, and
- a processor unit for controlling the optical system, the first emitter unit, and the second emitter unit,

- wherein the processor unit is configured to determine the positions of the optical components inside the photoresist layer, to elaborate a device pattern based on the positions of the optical components, and to fabricate the elaborated device pattern by locally exposing the photoresist layer to the first radiation.

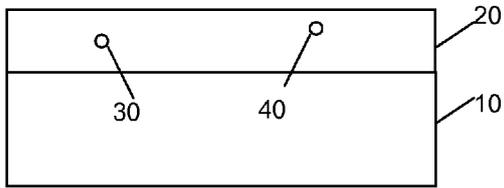


Fig. 1

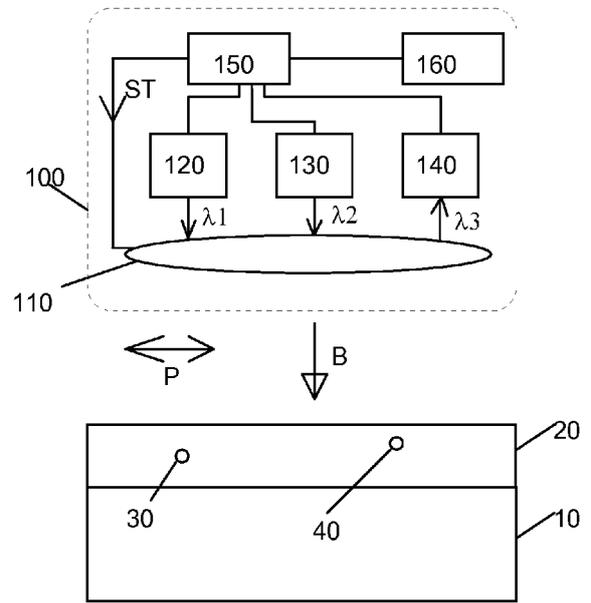


Fig. 2

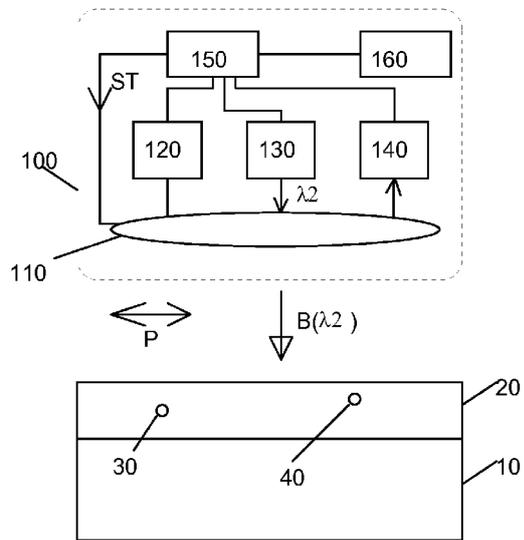


Fig. 3

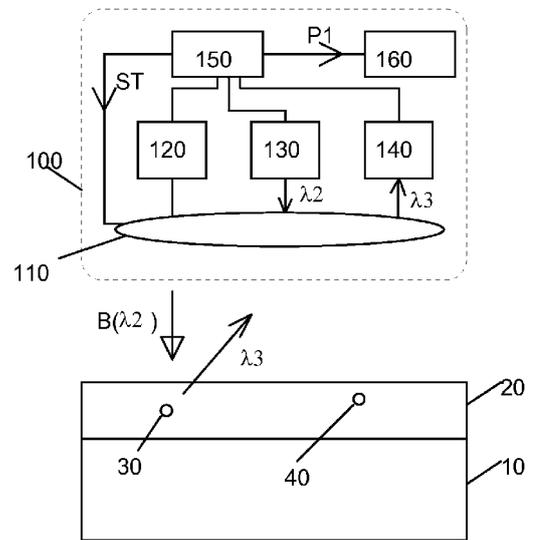


Fig. 4

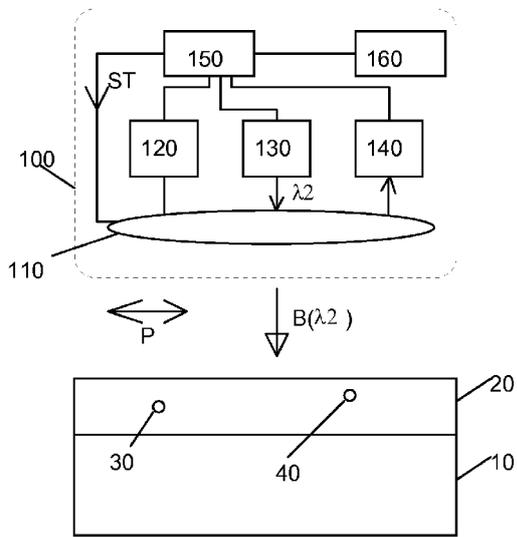


Fig. 5

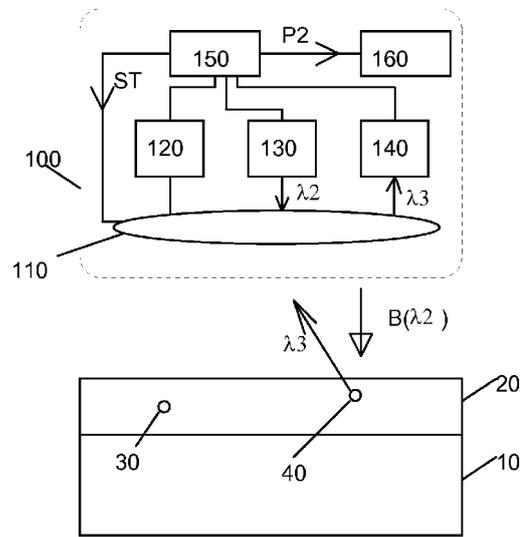


Fig. 6

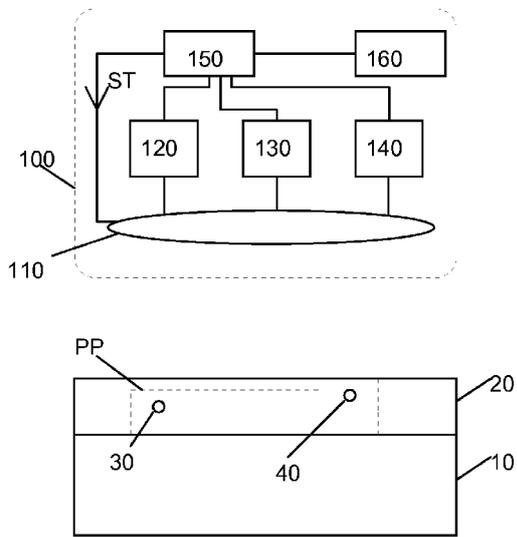


Fig. 7

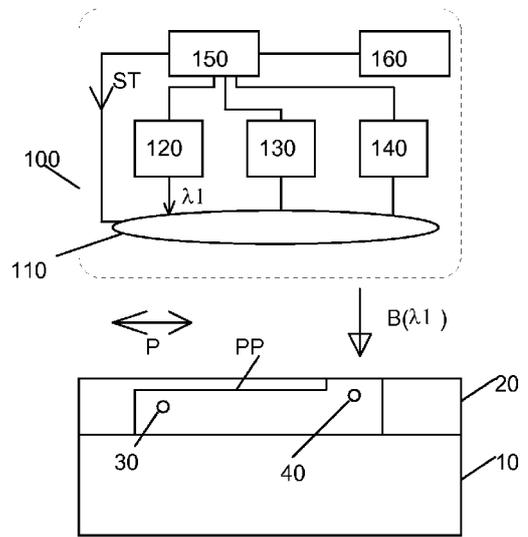


Fig. 8

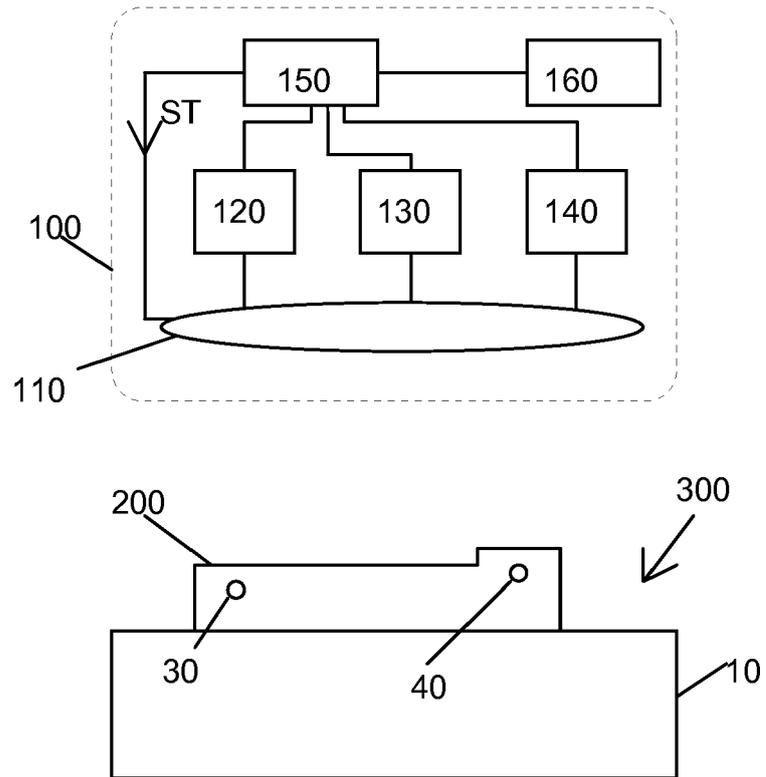


Fig. 9

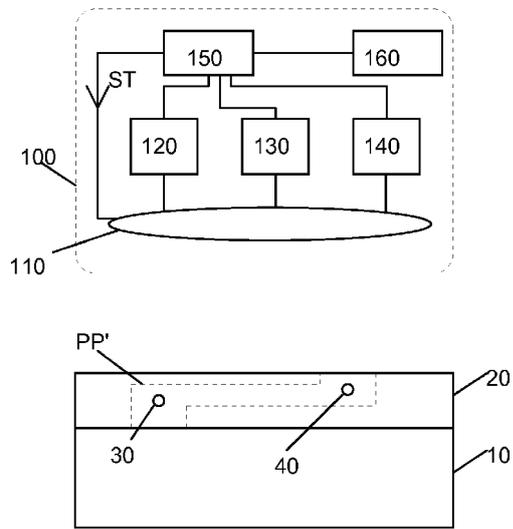


Fig. 10

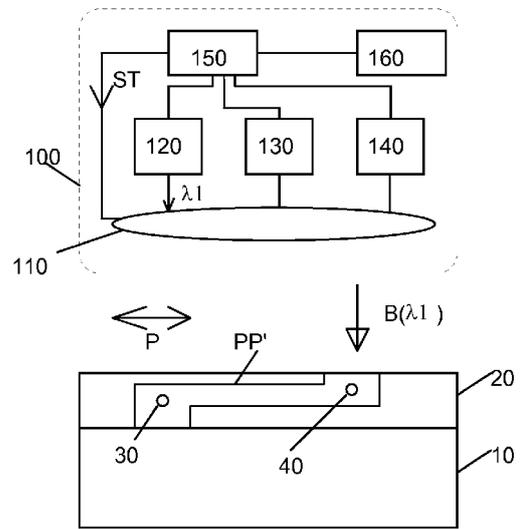


Fig. 11

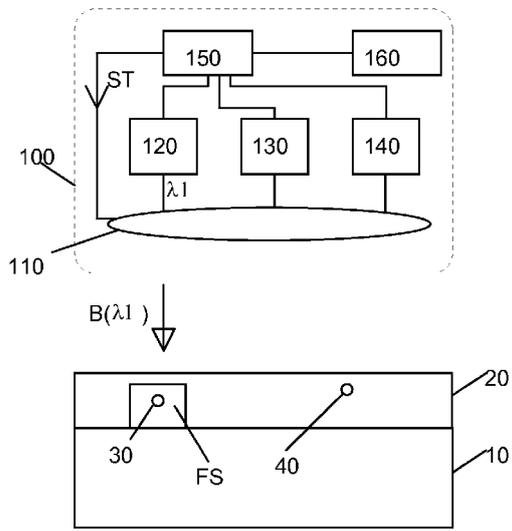


Fig. 12

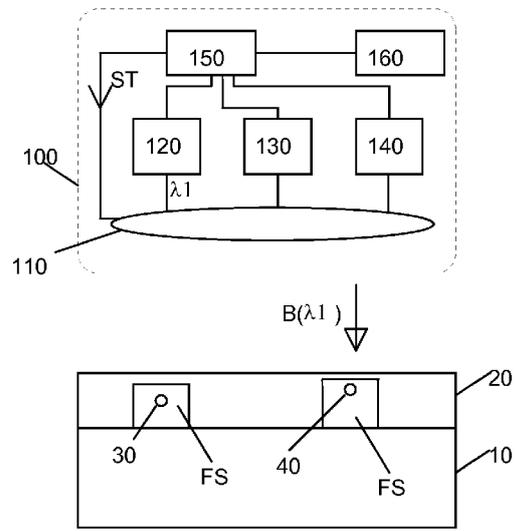


Fig. 13

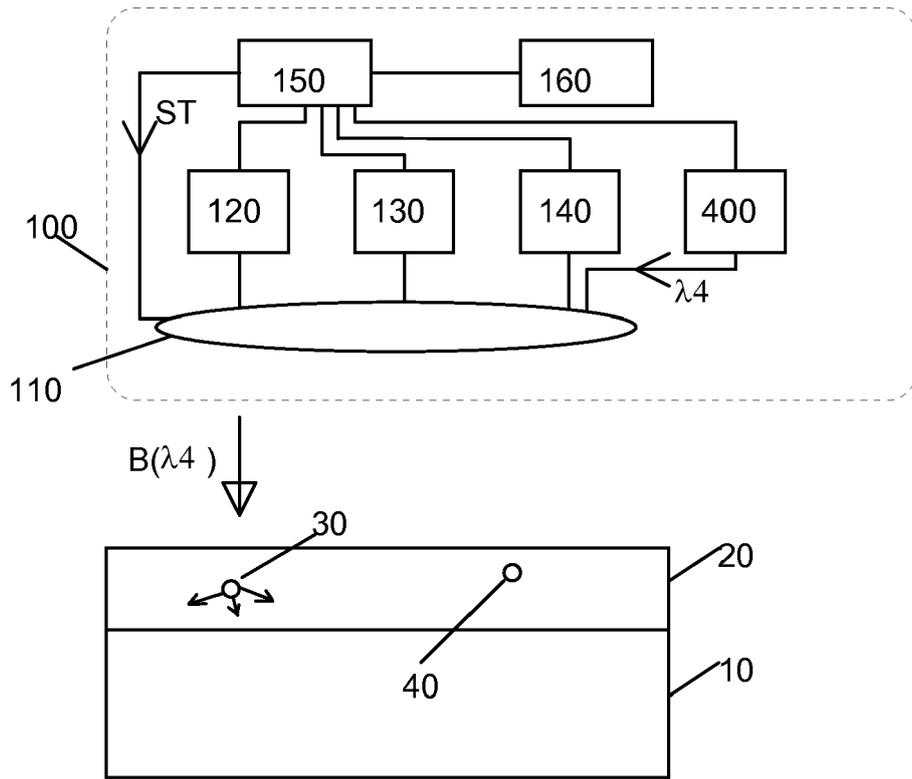


Fig. 14



EUROPEAN SEARCH REPORT

Application Number
EP 14 16 2345

5

10

15

20

25

30

35

40

45

50

55

| DOCUMENTS CONSIDERED TO BE RELEVANT | | | | |
|---|---|---|---|--|
| Category | Citation of document with indication, where appropriate, of relevant passages | Relevant to claim | CLASSIFICATION OF THE APPLICATION (IPC) | |
| X | US 2008/044127 A1 (LEISING GUNTHER [AT] ET AL) 21 February 2008 (2008-02-21) | 1,2 | INV. G02B6/138 G02B6/12 G02B6/42 | |
| Y | * abstract; figures 4,15 * | 3-13,15 | | |
| A | * paragraphs [0013], [0041] - [0043] * | 14 | | |
| ----- | | | | |
| X | JP 2003 315608 A (MATSUSHITA ELECTRIC WORKS LTD) 6 November 2003 (2003-11-06) | 1,2 | | |
| Y | * abstract; figures 1-3 * | 3-13,15 | | |
| | * paragraphs [0016], [0019], [0027], [0038]; claim 1 * | | | |
| ----- | | | | |
| Y | JP 2008 249913 A (PRECISE GAUGES CO LTD) 16 October 2008 (2008-10-16) | 3-13,15 | | |
| A | * paragraphs [0018], [0019]; figure 5 * | 14 | | |
| ----- | | | | |
| A | US 2004/047561 A1 (TUDA HIROYUKI [JP]) 11 March 2004 (2004-03-11) | 15 | | |
| | * abstract; figure 2 * | | | |
| | * paragraphs [0198] - [0200] * | | | |
| ----- | | | | |
| | | | TECHNICAL FIELDS SEARCHED (IPC) | |
| | | | G02B | |
| The present search report has been drawn up for all claims | | | | |
| Place of search Munich | | Date of completion of the search 31 July 2014 | Examiner Elflein, Wilhelm | |
| CATEGORY OF CITED DOCUMENTS | | T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document | | |
| X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document | | | | |

3

EPO FORM 1503 03.82 (PO4C01)

ANNEX TO THE EUROPEAN SEARCH REPORT
ON EUROPEAN PATENT APPLICATION NO.

EP 14 16 2345

5

This annex lists the patent family members relating to the patent documents cited in the above-mentioned European search report. The members are as contained in the European Patent Office EDP file on The European Patent Office is in no way liable for these particulars which are merely given for the purpose of information.

31-07-2014

10

| Patent document cited in search report | Publication date | Patent family member(s) | Publication date |
|--|------------------|-------------------------|------------------|
| US 2008044127 A1 | 21-02-2008 | AT 413891 B | 15-07-2006 |
| | | CA 2551654 A1 | 14-07-2005 |
| | | EP 1706770 A1 | 04-10-2006 |
| | | EP 2309294 A2 | 13-04-2011 |
| | | JP 2007517248 A | 28-06-2007 |
| | | KR 20060131816 A | 20-12-2006 |
| | | US 2008044127 A1 | 21-02-2008 |
| | | WO 2005064381 A1 | 14-07-2005 |
| ----- | | | |
| JP 2003315608 A | 06-11-2003 | NONE | |
| ----- | | | |
| JP 2008249913 A | 16-10-2008 | JP 4920473 B2 | 18-04-2012 |
| | | JP 2008249913 A | 16-10-2008 |
| ----- | | | |
| US 2004047561 A1 | 11-03-2004 | CA 2433873 A1 | 11-07-2002 |
| | | EP 1347317 A1 | 24-09-2003 |
| | | JP 3438140 B2 | 18-08-2003 |
| | | US 2004047561 A1 | 11-03-2004 |
| | | WO 02054120 A1 | 11-07-2002 |
| ----- | | | |

15

20

25

30

35

40

45

50

55

EPO FORM P0459

For more details about this annex : see Official Journal of the European Patent Office, No. 12/82

REFERENCES CITED IN THE DESCRIPTION

This list of references cited by the applicant is for the reader's convenience only. It does not form part of the European patent document. Even though great care has been taken in compiling the references, errors or omissions cannot be excluded and the EPO disclaims all liability in this regard.

Non-patent literature cited in the description

- **O'BRIEN, J. L. ; FURUSAWA, A. ; VUCKOVIC, J.** Photonic quantum technologies. *Nature Photon.*, 2009, vol. 3, 687-695 [0057]
- **BENSON, O.** Assembly of hybrid photonic architectures from nanophotonic constituents. *Nature*, 2011, vol. 480, 193-199 [0057]
- **BADOLATO, A. et al.** Deterministic coupling of single quantum dots to single nanocavity modes. *Science*, 2005, vol. 308, 1158-1161 [0057]
- **AOKI, K. et al.** Coupling of quantum-dot light emission with a three-dimensional photoniccrystal nanocavity. *Nature Photon.*, 2008, vol. 2, 688692 [0057]
- **KAWATA, S. ; SUN, H. B. ; TANAKA, T. ; TAKADA, K.** Finer features for functional microdevices. *Nature*, 2001, vol. 412 [0057]
- **DEUBEL, M. et al.** Direct laser writing of three-dimensional photonic-crystal templates for telecommunications. *Nature Mater.*, 2004, vol. 3 [0057]
- **LIU, Z. P. et al.** Direct laser writing of whispering gallery microcavities by two-photon polymerization. *Appl. Phys. Lett.*, 2010, vol. 97 [0057]
- **GROSSMANN, T. et al.** Direct laser writing for active and passive high-q polymer microdisks on silicon. *Opt. Express*, 2011, vol. 19, 11451-11456 [0057]
- **LEE, C.-W. ; PAGLIARA, S. ; KEYSER, U. ; BAUMBERG, J. J.** Perpendicular coupling to in-plane photonics using arc waveguides fabricated via two-photon polymerization. *Appl. Phys. Lett.*, 2012, vol. 100, 171102 [0057]
- **SUN, H. ; TANAKA, T. ; TAKADA, K. ; KAWATA, S.** Two-photon photopolymerization and diagnosis of three-dimensional microstructures containing uorescent dyes. *Appl. Phys. Lett.*, 2001, vol. 79, 1411 [0057]
- **LI, J. ; JIA, B. ; ZHOU, G. ; GU, M.** Fabrication of three-dimensional woodpile photonic crystals in a Pb-Se quantum dot composite material. *Opt. Express*, 2006, vol. 14 [0057]
- **SHUKLA, S. et al.** Subwavelength direct laser patterning of conductive gold nanostructures by simultaneous photopolymerization and photoreduction. *ACS Nano*, 2011, vol. 5, 1947-1957 [0057]